The European Institute for the PCB Community

EIPC SPEeDNEWS

The Weekly On-Line Newsletter
Issue 16 – May 2023

NEWS FROM THE EIPC

Supporting the PCB supply chain under the EU Chips Act.
EIPC Summer Conference, Munich, June 15-16.

A key attraction at **EIPC's Summer Conference** will be the presentation by **Stan Heltzel, Materials Engineer at the European Space Agency.** Stan is responsible for qualification of Printed Circuit Board manufacturers and technology development, and is the convenor of working groups on space standardisation.

The subject of his presentation is supporting the PCB supply chain under the EU Chips Act. It will describe a white paper, recently issued by Eurospace, calling for the wide strengthening of PCB technology and its supply chain in all market segments. It focuses attention on the weak European PCB ecosystem causing unavailability in its own supply chain. Raw materials are almost exclusively manufactured outside Europe, the workforce is difficult to maintain, education institutes do not offer adequate training, and critical equipment and chemistry need to be imported, which hampers the availability of senior service personnel from these overseas companies.

Here is an abstract of Stan Heltzel's paper:

"The number of PCB facilities in Europe has been continuously declining for several decades. Although in recent years the revenue appears to have stabilised, over a longer time span also this indicator follows a declining trend. About 60% of PCBs in Europe are imported, mostly from China. This dependency is most prevalent in volume markets, but also NewSpace equipment integrators are occasionally sourcing PCBs overseas, motivated by lower cost, shorter lead-time and in some cases a better capability. Qualification schemes and contractual conditions ensure local sourcing of PCBs in the high-reliability market segments of space and defence. For this low volume, high mix industry the most critical impact is an indirect one: the weak European PCB ecosystem causes unavailability in its own supply chain. Raw

materials are almost exclusively manufactured outside Europe, the workforce is difficult to maintain, education institutes do not offer adequate training, and critical equipment and chemistry need to be imported, which hampers the availability of senior service personnel from these overseas companies.

The end of a globalised market and the consequential reshoring has been initiated by the US-Chinese trade conflict and further deepened by the supply chain disruptions during the pandemic and the Ukrainian war. There is much excitement about the development of local chips technology and its ecosystem. The European Chips Act provides development opportunities from foundry to OSAT. But the act does not analyse the ecosystem beyond back-end packaging and is not inclusive of system level packaging, i.e. PCB technology and assembly. The global electronics industry struggles with the 'hidden reliability treat' in microvias. Yet it remains difficult to obtain development funds. This has caused critical failure of assembled flight electronics in several ESA projects. A state-of-the-art FPGA was developed and space qualified. But the routing of this part required microvias, which appeared to be failing. Not only the malfunctioning modules were scrapped, but also other - working - modules from batches that were affected by this microvia weakness. This presentation will describe a white paper, recently issued by Eurospace, calling for the wide strengthening of PCB technology and its supply chain in all market segments."

For full details of the EIPC Summer Conference, check the EIPC website www.eipc.org

Pete Starkey
I-Connect007

The European Institute for the PCB Community

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NEWS FROM ISRAEL

Eltek Ltd. Reports 2023 First Quarter Financial Results

PETACH TIKVA, Israel, May 18, 2023 /PRNewswire/ -- Eltek Ltd. (NASDAQ: ELTK), a global manufacturer and supplier of technologically advanced solutions in the field of printed circuit boards (PCBs), today announced its financial results for the quarter ended March 31, 2023.

First Quarter 2023 Highlights
Revenues were $11.5 million, 18% up over Q1 2022 Operating profit was $1.6 million, 144% up over Q1 2022 Profit before tax was $1.9 million (2022 Q1 - $0.8 million)

Net income was $1.6 million or $0.27 per fully diluted share, 147% up over Q1 2022

Net cash provided by operating activities amounted to $2.8 million

“Eltek is proud to announce its strong first quarter results for 2023, with growth of 18% in sales compared to the same quarter last year, and an impressive 147% increase in net income. These results are a testament to the success of the Company’s strategy to invest in innovative equipment to increase production volumes, and an unwavering commitment to product quality to meet customer satisfaction and provide technological solutions for every customer’s needs. As of today our backlog increased 10% from the beginning of the year.

Our strong cash flows from operating activities in the first quarter of $2.8 million allowed us to repay $1.6 of our long-term debt and consequently lower our interest expenses, given the current high rates,” said Eli Yaffe, CEO of Eltek.

“Throughout the quarter, we continued to execute on our accelerated investment plan and ordered three new plating lines valued at 5.5 million Euros. The deployment of these coating lines is scheduled for the latter half of 2023, 2024 and 2025, which will enable the simultaneous additional enhancement of production capacity, efficiency, and diversification of our product offerings,” continued Mr. Yaffe.

“Concurrently with our accelerated investment plan, we are also allocating resources towards acquiring additional machinery and equipment, as well as enhancing our manufacturing procedures. These endeavours supported the increase in both revenues and net income, resulting in our quarterly net income of $1.6 million,” concluded Mr. Yaffe.

First Quarter 2023 GAAP Financial Results

Revenues for the first quarter of 2023 were $11.5 million, compared to $9.8 million in the first quarter of 2022;

Gross profit for the first quarter of 2023 was $3.0 million (26% of revenues) compared to $2.0 (20% of revenues) in the first quarter of 2022;

Operating profit for the first quarter of 2023 was $1.6 million compared to operating profit of $0.7 million in the first quarter of 2022;

Profit before income tax for the first quarter of 2023 was $1.9 million compared to $0.8 million in the first quarter of 2022;

Net income for the first quarter of 2023 was $1.6 million or $0.27 per fully diluted share compared to net income of $0.6 million or $0.11 per fully diluted share in the first quarter of 2022;

First Quarter 2023 Non-GAAP Financial Results

EBITDA for the first quarter of 2023 was $1.9 million (17% of revenues) compared to EBITDA of $1.1 million (11% of revenues) in the first quarter of 2022.

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NEWS FROM JAPAN

MKS' Atotech to participate in JPCA Show

Berlin, May 19: – Today, MKS Instruments is excited to join the upcoming JPCA Show at Tokyo Big Sight held from May 31 to June 2, 2023. The team will represent our strategic brands, Atotech and ESI, and will introduce our latest products and manufacturing solutions for PCB and package substrate manufacturing.

Atotech
MKS Atotech and ESI teams are represented by a select group of industry and technology experts from across various business sectors and can be found at booth 6B-11. We are looking forward to learn about your latest requirements and explain what we can do for you with our new combined product offering.
MKS is highly committed to driving next-level technological developments within its industries and key installations at our local TechCenter in Yokohama to support next generation package substrate development working towards meeting 5/5µm L/S targets. By combining leading capabilities in lasers, optics, motion, process chemistry and equipment, we are positioned to Optimize the InterconnectSM, a significant enabling point of next-generation advanced electronics that represents the next frontier for miniaturization and complexity.

Our show highlights include:
G-Plate®: Vertical desmear and electroless HVM plating tool for next-generation high-end package substrates with well-organized particle control
Cuprapulse® XP7-IN: Vertical pulse plating with inert process to improve thickness distribution, especially high and low TH density area and very suitable for inner layer of next-generation package substrates

NovaBond® EX-S2: Adhesion Promoter for the latest ABFs with zero-line width reduction and minimized surface nano-roughness. Very suitable for ultra-fine lines and high frequency applications due to its nearly impeccable signal integrity
Stanna-CAT®: New autocatalytic tin bath with no thickness limitation and no selectivity of plated metal
Geode® A: CO2 laser system for high precision and high-speed ABF build-up laminate processing
CapstoneTM: Flex PCB UV drilling tool for high-performance breakthrough productivity

Conference: JPCA Show 2023
Date: May 31, to June 2, 2023
Booth: 6B-11
Venue: Tokyo Big Sight (East Exhibition Halls)

For more information on the JPCA Show, please visit: JPCAshow.com

About MKS Instruments
MKS Instruments enables technologies that transform our world. We deliver foundational technology solutions to leading edge semiconductor manufacturing, electronics and packaging, and specialty industrial applications. We apply our broad science and engineering capabilities to create instruments, subsystems, systems, process control solutions and specialty chemicals technology that improve process performance, optimize productivity and enable unique innovations for many of the world's leading technology and industrial companies. Our solutions are critical to addressing the challenges of miniaturization and complexity in advanced device manufacturing by enabling increased power, speed, feature enhancement, and optimized connectivity. Our solutions are also critical to addressing ever-increasing performance requirements across a wide array of specialty industrial applications.

About ESI
ESI is a brand within the Photonics Solutions Division of MKS Instruments. ESI systems deliver market-leading solutions for Flexible PCB laser processing, high-speed MLCC testing, and CO2-laser-based systems for HDI PCB and IC substrate manufacturing. ESI solutions help manufacturers optimize production of the materials, components and systems that are an integral part of the electronic devices in use today. They deliver greater flexibility and a higher degree of processing control, enabling customers to incorporate a wider range of materials into their production processes. The result is higher

production quality, increased throughput and higher yields at a lower total cost of ownership.

About Atotech

Atotech, a brand within the Materials Solutions Division of MKS Instruments, develops leading process and manufacturing technologies for advanced surface modification, electroless and electrolytic plating, and surface finishing. Applying a comprehensive systems-and-solutions approach, the Atotech portfolio includes chemistry, equipment, software, and services for innovative and high-technology applications in a wide variety of end-markets. With its innovative strength and industry-leading global TechCenter network, MKS delivers pioneering solutions through its Atotech brand – combined with unparalleled on-site support for customers worldwide.

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NEWS FROM ELECTRONICA

EUROPEAN CHIPS ACT

With many billions, Europe aims to become more independent with regards to semiconductors. The goal is to double the global market share in chips from 10 to at least 20 percent by 2030. But not all share this optimism.

Europe is highly dependent on chips from Asia and the USA. Of the USD 580 billion worth of semiconductors produced in 2020, just ten percent came from the EU. The consequences of this came to light during the coronavirus pandemic: Supply bottlenecks and even interruptions in the industry and other strategic sectors such as health, defence and energy. Another threat is that, against the background of growing geopolitical tensions, semiconductor production is increasingly serving strategic goals. This development is being further fuelled by the high demand for microchips, which remains undiminished.

ZVEI expects the global semiconductor market to double to USD one trillion by 2030. The long-term demand for chips remains high, especially in the feature sizes relevant for the automotive and industrial markets. Digitalization and green transformation are also driving this growth.

EU Chips Act – A booster for the world market share

To cover the growing demand and strengthen the overall semiconductor value chain, the “EU Chips Act” now aims to double the European world market share from the current 10 percent to 20 by 2030.

According to Bitkom, this support for the European semiconductor industry is long overdue. And the announced EUR 43 billion, of which only 3.3 billion comes from the EU budget and the rest from public and private pots, is

comparatively small. After all, the US Chips Act of 2022 includes an investment volume of around USD 52 billion. And the Chinese government is estimated to be pouring USD 150 billion into its semiconductor industry by 2025. Europe is thus comparatively late and is “stingy” with its resources. Rapid implementation will therefore be all the more important.

New gigafactories in Germany

In concrete terms, delays could jeopardize Intel’s EUR 17 billion factory plans in Magdeburg. The first next-generation chips are to roll off the production line there by 2027. According to the Minister President of Sachsen Anhalt, Reiner Haseloff (CDU), the adoption of the Chips Act represents a new legal basis for the payment of necessary subsidies, without which it would not be possible for relevant companies to set up shop.

This is already happening elsewhere. For example, the groundbreaking ceremony for a EUR 5-billion plant by Infineon recently took place in Dresden. The group is building a 300-millimeter smart power factory for analog/mixed-signal technologies and power semiconductors. This combination enables particularly energy-efficient and intelligent power supply solutions.
The US Group Wolfspeed – a market leader in silicon carbide (SiC) and gallium nitride (GaN) technologies – is also investing in Germany. In Saarland, EUR 2.75 billion – the majority of which is subsidized – are flowing into the world’s largest plant for SiC power semiconductors. The transmission manufacturer ZF has a minority stake in the factory.

Doubts about the EU Chips Act

Not everyone is entirely happy with the EU Chips Act. ZVEI, for example, complains that only a small part of the planned EUR 43 billion comprises completely new funds. Funds for research and development, for example, are the result of postponements of funding amounts that have already been planned. In addition, the focus on feature sizes below ten nanometers is too narrow and ignores the needs of the European buyer industry. After all, power electronics and sensors will contribute significantly to the success of the green and digital transformation.

The VDMA also sees mechanical engineering – one of the largest European industrial sectors – needing feature sizes above 16 nanometers by the end of 2030. The focus, they say, should therefore not only be on factories for 2-nanometer chips (“cutting edge chips”), but also needs to reflect the entire breadth of the European industry.

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NEWS FROM TAIWAN

Dark cloud over AI revolution: the cost

The explosion of generative artificial intelligence (AI) has taken the world by storm, but one question all too rarely comes up: Who can afford it?
OpenAI Inc bled about US$540 million last year as it developed ChatGPT and said it needs US$100 billion to meet its ambitions, according to industry media The Information.

“We’re going to be the most capital-intensive start-up in Silicon Valley history,” OpenAI founder Sam Altman told a panel recently.

When Microsoft Corp, which poured billions of dollars in investment into OpenAI, was asked about how much its AI adventure would cost, the company answered with assurances that it is keeping an eye on its bottom line.

Building something even near the scale of what OpenAI, Microsoft or Google have on offer would require an eye-watering investment on state-of-the-art chips and recruiting prize-winning researchers.

“People don’t realize that to do a significant amount of AI things like ChatGPT takes huge amounts of processing power. And training those models can cost tens of millions of dollars,” independent analyst Jack Gold said.

“How many companies can actually afford to go out and buy 10,000 Nvidia H100 systems that go for tens of thousands of dollars a piece?” Gold asked.

The answer is pretty much no one and in tech, if you cannot build the infrastructure, you rent it and that is what companies already do massively by outsourcing their computing needs to Microsoft, Google and Amazon Web Services.

With the advent of generative AI, this dependency on cloud computing and tech giants deepens, leaving the same players in the driver's seat, experts said.

The unpredictable costs of cloud computing "is a heavily underestimated problem for many companies," Software AG chief product officer Stefan Sigg said.

Sigg compared cloud costs to electricity bills and said companies that do not know better are in for "a big surprise" if they let their engineers run up bills in the mad rush to build tech, including AI.

Microsoft's signature cloud offer is Azure and some observers believe the giant's all-in bet on AI is really about protecting Azure success and guaranteeing the cash cow's future.

Azure has been the giant's unsexy bread-winner for years, bringing in huge profits, but without attracting the headlines of an iPhone or social media that go straight to the consumer.

For Microsoft, "the golden goose is monetizing cloud with Azure, because we're talking about what could be a US$20, US$30, US$40 billion opportunity annually down the road if the AI bet is successful," Wedbush Securities Inc analyst Dan Ives said.

Microsoft CEO Satya Nadella said that generative AI is "moving fast in the right direction."

Deeply respected on Wall Street, Nadella would have a six or nine-month grace period to show his bet is a winner, Ives said.

Microsoft acknowledges the risk, but insists that on AI, it must "lead this wave," chief financial officer Amy Hood told analysts this month.

"We will charge for those AI capabilities, and then ultimately, we'll deliver operating profit," she said.

Piling up profit at the company founded by Bill Gates can only mean passing on the cost of AI to customers. From Main Street to Fortune 500, the dependency on the AI-amped would be an expensive one, and companies and investors are drumming up alternatives to at least reduce the bill.

"AI training, GPT training will become a very important cloud service going forward," Spectro Cloud CEO Tenry Fu said.

His company, like many others in the sector, helps companies optimize cloud technology to reduce expenses.

“But after training, a company will be able to get their model back for real AI application” and the dependence on the cloud giants will hopefully be reduced, he added.

Regulators are hoping that they can keep up and not leave the giants in charge, imposing their terms on smaller companies.

“Law enforcers [must] ensure that ... opportunities and openings for competition ... are not getting squashed out by the incumbents,” US Federal Trade Commission Chairwoman Lina Khan told CNBC

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NEWS FROM THE UK

It with great sadness that we report on the death of Martin Cotton, one of the PCB industry's great contributors, and memorable characters. The obituary shown below was written by Philip Stoten, who knew him well.

This last weekend industry guru and dear friend to many Martin Cotton passed away. He was one of the first people I worked with in the electronics industry when I joined Toptec Design to learn to layout PCBs. He was a bit of a rockstar to many PCB designers, myself included. He was known to be among the best in his field, if not the best, and went on to be one of the most influential and innovative people in the industry over a long and distinguished career. He will be hugely missed by his family and by his numerous friends in and out of the electronics industry.

Over five decades Martin performed his magic at companies including Nortel Networks, Viasystems, Sanmina and Ventec International Group, racking up numerous patents along the way and sharing his intellect and his energy and passion for the industry with trade associations like the ICT (Institute of Circuit Technology) and EIPC (European Institute of Printed Circuits), for whom he spoke on numerous occasions. Less than six months ago, Steve Driver of the ICT presented him with an Honorary Fellowship. Steve Driver said at the time, "Martin has been a huge contributor to the Institute of Circuit Technology for many years. He is a recognised industry expert and is very worthy of this accolade."

Those that knew Martin as I did, will remember him primarily as the

exuberant fun loving friend that always had your back, and was always up for a big night out, especially if you were lucky enough to spend an evening with him in Munich, after a long day at electronica or productronica. As someone I consider a life-long friend, that's how I remember him, but Martin was so much more than just a wonderful friend. I don't think many would disagree if I said he was a genius and an innovator in his field. When we talked about technology I was always trying to keep up and it seems the entire industry was too. Martin proved it was possible to be too far ahead of the field, and perhaps a little too smart for the rest of the room!

I spent more than forty years of my career sharing thoughts, ideas and more than a few beers with Martin. He was a mentor, a dear friend and someone I could always count on. I loved working with him and just being in his orbit, where he was the star of the show. I interviewed him on numerous occasions on camera (take a look at those interviews if you find time), and I spent many many great evenings with him just talking and laughing. He always made me think and he always made me smile.

I am going to post this to LinkedIn and encourage his numerous friends and colleagues to comment, then perhaps we can round out a tribute to this guru, this genius and this diamond geezer!

Martin we love you and we miss you.

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NEWS FROM THE UK

PFAS statement from Ventec.
The European Chemicals Agency (ECHA) proposed restriction of per- and polyfluoroalkyl substances (PFASs)

The EU, through ECHA, is proposing restrictions on around 10,000 per- and polyfluoroalkyl substances (PFASs).

Documentation including the full list of substances covered is available on the ECHA website here: https://echa.europa.eu/registry-of-restriction-intentions/-/dislist/details/0b0236e18663449b.

ECHA's scientific committees for Risk Assessment (RAC) and for Socio-Economic Analysis (SEAC) are underway with their scientific evaluation of the proposal. RAC will form an opinion on whether the proposed restriction is appropriate in reducing the risks to people's health and the environment, while SEAC's opinion will be on the socio-economic impacts, i.e. benefits and costs to society, associated with the proposal. Both committees form their opinions based on the information in the restriction proposal and the comments received during the six-month consultation period which started in March 2023.

The class of PFASs includes the synthetic fluoropolymer PTFE (polytetrafluoroethylene) which will be restricted from sale, use or manufacture in the EU when and if the proposal is implemented in its current form. PTFE has unique properties which means that there are no currently available direct substitutes giving equivalent performance in certain use cases in the materials supply chain.

Nonetheless Ventec continues to develop new low-loss materials to close the performance gap to PTFE without the use of PFASs. Derogations have already been addressed in the proposal which may include an 18-month transition period for all the PFASs covered plus either a five or twelve year derogation period for some uses after the EIF (entry into force) date which will likely be 2025/2026.

Moreover, EU REACH regulations allow exemptions for member states from the regulations where necessary in the interests of defence which may well be relevant for certain sensitive electronics use cases.

It should be noted that the UK no longer participates in the ECHA or EU REACH regulatory framework there is therefore no automatic adoption of new EU REACH restrictions, under which the proposed restrictions would be introduced, in UK REACH regulations.

Ventec will continue to monitor the proposed restrictions of PFASs and will provide updates as they become available.

InstaDeep Ltd. (London, England) offering a free PCB design service for electronics companies.

AI startup InstaDeep Ltd. (London, England) is offering a free PCB design service to electronics companies.

Engineers upload schematics in the '.dsn' file format and receive layout files for the board within 24 hours.
DeepPCB is a beta release of software that generates layout files for two-layer printed circuit boards and is compatible with KiCad. KiCad is a free EDA software suite that includes schematic capture, PCB layout, manufacturing file viewing, SPICE simulation, and engineering calculation.

The PCB routing engine that makes use of AI technology from InstaDeep combined with cloud infrastructure. Results are provided within 24 hours.

DeepPCB operates without human intervention using reinforcement learning to achieve an optimized result. Customers can access intermediate routing solutions.

On its website the company promises: “InstaDeep will never share or sell any of your data to any outside entity. Our sole goal is to accelerate your PCB product development cycle. For now, we have released a free beta version but we’re working on a commercial version to tackle larger and more complex boards. We anticipate keeping a free version to make it easier for hobbyists to design their boards.”

Another company working on AI for PCB design is Circuit Mind Ltd. although its product works on the path from architecture to schematic.

By Peter Clarke

eeNews Europe

News from
WECC members

WECC
World Electronic Circuits Council

Issue 16 – May 2023

NEWS FROM THE IPC

Dear Colleague,

I'm reaching out to ask for your personal attention to an urgent call-to-action that IPC, in conjunction with IPC's industry-led environmental steering council, issued this week.

The call-to-action urges electronics manufacturers to provide data and information on the industry's use of chemicals known as perfluoroalkyl and polyfluoroalkyl substances (PFAS). The European Chemicals Agency (ECHA) is proposing the **broadest ban** in its history, phasing out **manufacturing and use of thousands of** PFAS by 2026 under the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) Regulation. This ban will impact PFAS manufacturers as well as downstream users of PFAS-containing products, including those companies engaged in electronics manufacturing.

ECHA is requesting technical and detailed data during a stakeholder consultation period through September 2023 to understand PFAS uses, criticality, and potential for alternatives. **With appropriate data, ECHA will be able to**

determine whether uses qualify for a time-limited exemption from the ban. Without data, ECHA is left to assume the impact on downstream users in the electronics industry will remain minimal when PFAS is banned. As of now, ECHA is proposing a baseline restriction in which there will be a universal ban with no exemptions for the electronics industry. Unless we come forward with appropriate data and information on uses and alternatives, **we should anticipate a complete ban and the electronics industry going PFAS-free by 2026**.

IPC has engaged the industry over the past six months to raise awareness and secure industry data, but we have not received sufficient information to enable advocacy. We are asking that you evaluate this issue regarding your products and your suppliers, to determine if PFAS are used and whether they are critical for the manufacturing and quality of your products.

We have approached a **"now or never moment."** We encourage you to read and share our **Call to Action Statement** and discuss it with relevant technical experts and suppliers to determine whether PFAS can be found in your products and supply chains. For IPC to effectively compile and analyze data for inclusion in an initial submission to European regulatory authorities, we need detailed data — or a commitment to being able to identify and submit the appropriate data — **by 19 May 2023.** More information on deadlines is outlined in our statement as well as additional information on the REACH restriction activity. **This is a pivotal**

moment for the industry on this issue. For IPC to credibly advocate for exemptions on this ban, we need your data now.

If you have any questions or would like to follow up on this call to action, please reach out to IPC's Environmental Regulatory Affairs Manager, Suhani Chitalia at SuhaniChitalia@ipc.org.

Sincerely,

John W. Mitchell
IPC President and CEO
JohnMitchell@ipc.org

NEWS FROM THE TPCA

Taiwan's latest progress of a number of PCB enterprise projects -

May 16, 2023
TPCA

01 Eaton Electronics
Eaton Electronics recently said in an institutional survey that the first phase of the company's digital intelligent new factory project completed equipment installation, commissioning and trial production in the first quarter of 2022, and began mass production in the second quarter. The construction of the new factory is divided into two phases, with a total planned production capacity of more than 200 million square meters / year, mainly used for the production of high-end automotive PCB, new energy PCB and photovoltaic PCB. At present, the production capacity of the first phase of the project is progressing smoothly, and the production capacity is gradually released.

02 Chaohua Technology
Chaohua Technology said in an institutional survey on May 5 that at present, the construction of the first phase of the Yulin project in Guangxi is steadily advancing, and the plant construction has been completed, and trial production can be completed after the equipment enters the site to complete assembly and debugging, and the products are mainly copper foil and copper clad laminate.
15 Hudian Co., Ltd.

Hudian Co., Ltd. said in an institutional survey on May 03 that as overseas customers pay more attention to and strengthen the implementation of the geo-supply chain risk diversification strategy, multi-regional risk dispersion operation capabilities may gradually become the key to the future growth of the industry, and the company has purchased about 5,15.201 square meters of land located in the Ayutthaya Industrial Park in Logana, Thailand.

In order to meet the future project construction needs of the company's Thai subsidiary. The company will accelerate the process of manufacturing in Thailand and has started infrastructure construction to bring forward its large-scale production plan from the first half of 846 to the fourth quarter of 8.
2025

Zhongyi Technology Zhongyi Technology
said on the investor interactive platform on May 2024 that the company's composite current collector project is in the pilot line construction stage, and the company is actively promoting the research and development and production of composite current collector.

04 Zecheng Electronics
Zecheng Electronics said in a recent institutional survey that as of December 5, 15, the company's "Zecheng Electronic Intelligent Control Module Construction Project" has invested a total of 05,2022,12.31 yuan. Huizhou Zecheng Technology Co., Ltd. (hereinafter referred to as "Huizhou Zecheng") is the main implementation body of the company's intelligent module production base construction. The project construction shall be carried out in the order of plant No. 34 and supporting dormitory and plant No. 995. At present, the engineering project of No. 587 plant and dormitory has been completed, and the secondary decoration project has been started; The ground hardening of plant No. 12 has been completed and entered the project construction planning period. During the reporting period, Huizhou Zecheng began to purchase relevant production equipment batch by batch according to the progress of plant construction.

1 Guangyunda
Guangyunda said on the investor interactive platform on May 2 that the aviation manufacturing base of Guangyun Dadu has been structurally capped, and it is expected to complete the overall relocation by September 1.
(Source: CPCA printed circuit information)

EIPC SPEeDNEWS

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International Diary

2023

EIPC Summer Conference
Visit BMW World
15 & 16 June
Munich, Germany

22nd EIPC Technical Snapshot Webinar
Registrations via www.eipc.org
September

23rd EIPC Technical Snapshot Webinar
Registrations via www.eipc.org
October

EIPC @ Productronica 2023
Stand B3-529
14-17 November
München, Germany

24th EIPC Technical Snapshot Webinar
Registrations via www.eipc.org
December